Proforma

Companies open to your department

Company : Taiwan Semiconductor Manufacturing Company Company Name : Taiwan Semiconductor Manufacturing Company

Nature Of Business: Semiconductor

Designation: Design/process co-optimization and R&D Engineer

Tentative Job Location :

Hsinchu City, Taiwan

Responsibilities

- R&D in 5nm/3nm/3DIC/HPC design and process co-optimization
- EDA enablement, design and sign-off methodology development
- R&D, innovation and path-finding
- Quality infrastructure development and project/program management
- Customer design flow support

NΤ

NT NT

Requirements

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Description:

- Familiar with process fabrication, CAD, algorithm, EDA tool, APR, timing, IR/EM, low power, physical verification, device modeling, Â VLSI chip implementation or 3DIC
- Innovative and prolific in patent filing or paper publication
- Timing/power sign-off methodology and library characterization
- IR-dorp analysis, power calculation, DC and AC Electro-migration check and fixing
- 3DIC innovation, implementation, optimization, process design kit and system design solution
- Quality infrastruce development, quality control and project/program management

Department BT BS MT DoubleMajor dual dualB dualC Mdes MBA Phd MSc MSR

NΤ

NT

AE	Ν	-	Ν	N	Ν	N	N	-	-	Ν	-	Ν
BSBE	N	-	N	N	N	N	N	-	-	N	-	N
CE	N	-	N	N	N	N	N	-	-	N	-	N
CHE	N	-	N	N	N	N	N	-	-	N	-	N
CSE	N	-	Y	N	Y	Y	Y	-	-	Y	-	Y
EE	N	-	Y	N	Y	Y	Y	-	-	Y	-	Y
ES	-	N	N	-	N	-	N	-	-	N	-	-
ME	N	-	N	N	N	N	N	-	-	N	-	N
MSE	N	-	Y	N	Y	Y	Y	-	-	N	-	Y
PHY	-	N	-	N	N	N	N	-	-	N	N	-
CHM	-	N	-	N	N	N	N	-	-	N	N	-
MTH	-	N	-	N	Y	Y	Y	-	-	Y	Y	-
ECO	-	N	-	N	N	N	N	-	-	N	-	-
DES	-	-	-	-	-	-	N	N	-	N	-	-
IME	-	-	N	-	-	N	N	-	N	N	-	-
CGS	-	-	-	-	-	-	-	-	-	N	-	N
HSS	-	-	-	-	-	-	-	-	-	N	-	-
EEM	-	-	N	-	-	N	-	-	-	N	-	-
MSP	-	-	Y	-	-	-	-	-	-	N	-	-
NET	-	-	N	-	-	N	-	-	-	N	-	-
PSE	-	-	Y	-	-	Y	-	-	-	N	-	Y
Stats	-	-	-	-	-	-	-	-	-	Y	Y	-

Item (Annual)	Master Degree	Ph.D. Degree						
GROSS	\$Â Â Â Â Â Â Â Â Â Â Â Â Â 49,813	\$Â Â Â Â Â Â Â Â Â Â Â Â 68,160						
СТС	\$ÂÂÂÂÂÂÂÂÂÂÂÂÂÂ 58,913	\$Â Â Â Â Â Â Â Â Â Â Â Â 84,400						

Eligibilty:

Cost to Company:

Package Details:

Currency: USD

- Including 12 months base pay, 2 months Year-end bonus, 18 months Profit Sharing, Design Incentive Bonus, 2 months relocation bonus, 4-6 months sign on bonus.
- Base Salary, Year-end bonus, Design Incentive Bonus are fixed and recurring.
- Profit Sharing is minimum amount for an average performance (i.e. top 50%) and recurring.
- Relocation and sign on bonus are one shot paid after onboard.

Bond: True

Bond Details: 24 months

Medical

Requirements:

Resume Shortlist : True
Resume Shortlist

Criteria:

N/A

Aptitude Test: False
Group Discussion: False
Technical Test: False
Technical Interview: True

Technical Interview

Duration:

60 mins

Number of Techincal 1 Interview Rounds:

HR Interview: True

HR Interview

60 mins

Duration: